Frequently Asked Questions

General

Question: What standards are covered by your product offering?
ANSWER: Our product portfolio is intended to address all the major digital cellular standards. This includes, but is not limited to: GSM, IS-136, DECT, and CDMA. In addition, our products are capable of supporting the AMPS standard as well as other wireless applications including two-way pagers, digital cordless phones, and ISM band products.

QUESTION: What process technologies are utilized?
ANSWER: TI utilizes the process technology that best satisfies the requirements. We use both silicon and gallium arsenide processes. Silicon processes include both an RF specific CMOS process called RFMOS(as well as BiCMOS processes. A variety of gallium arsenide processes are available to us.

QUESTION: Do you offer both die and packaged devices?
ANSWER: Our present focus is to provide plastic packaged devices in industry standard form factors (SSOP, TSSOP, SOT-89, etc.). However, TI is interested in discussing the delivery of die under mutually agreeable conditions.

QUESTION: What package types are available?
ANSWER: Present product offerings are housed in industry standard form factors such as the TSSOP and SOT-89 packages. In addition, TI offers a thermally enhanced version of the TSSOP package called PowerPAD.

QUESTION: What's PowerPAD(?
ANSWER: PowerPAD™ packages are designed to optimize the heat transfer to the PWB. A thermal pad is formed using a leadframe design (patent pending) and manufacturing technique to provide the user with direct connection to the die pad. When this die pad is soldered or otherwise connected to a heat-sink under the package, heat dissipation is increased over conventional surface mount packages of the same type.

QUESTION: Is the thermal pad on the PowerPAD required to be attached to the PCB?
ANSWER: The thermal pad acts as both a transfer means for heat as well as a common electrical ground for the circuit. To achieve the best electrical performance, the thermal pad must be connected to the PCB. For amplifier products it is basically a requirement to connect the PCB and the pad. TI plans to offer other types of products in this package, such as synthesizers. Although not a requirement from a thermal perspective to connect the pad for these types of devices, improved electrical performance can be achieved.

QUESTION: What type of application notes are available?
ANSWER: Application notes for each release product is available as well as notes on related topics. Please visit our Web page to access these documents.

QUESTION: Why are my test results different than your datasheet?
ANSWER: Several factors can provide for variation in test results. The information contained in the datasheet is a composite of many devices. Your test results are likely from a smaller sample size, and may result in better, or worse, performance. However, guaranteed parameters should always meet or exceed the specification. Other possible test result variation factors are: differences in test equipment and calibration procedures chip to chip differences support component variations

QUESTION: Can I use different components for my board?
ANSWER: It is possible to use components different than those specified in our product literature. However differences in performance may result. TI makes every effort to use components that are readily available and used throughout industry. Application notes also detail possible trade-off's in component types and values as well as board layout variations.

QUESTION: Are evaluation boards available?
ANSWER: Evaluation boards are available for all of our released products. Under mutually agreeable conditions, we also provide evaluation boards for products in development. Evaluation boards for released products are available via our Web page or your local TI field sales office. Please contact the sales office for information on evaluation boards for devices in development.

QUESTION: Do you have a cross-reference matrix?
ANSWER: A cross-reference matrix of TI's product offering to competitive devices is not available. Due to the nature of power amplifiers, a "drop in replacement" for any vendor's device is unlikely. However, please contact your local TI field sales office for assistance in determining the TI product for a given competitive offering.

QUESTION: What are your future product plans?
ANSWER: Information on future products is available on our Web page.

QUESTION: How do I get information on your products?
ANSWER: Information is available in a variety of ways. Our Web page is a good place to start. Your local TI field sales office is also available to help you with product information. TI also provides literature in paperback form as well as CD format.